1. **MATERIAL:**
   - **HOUSING:** POLYESTER MOLDING COMPOUND, UL 94-VO, COLOR: BLACK
   - **TERMINALS:** 0.35 [0.0135] THICK PhOS BRONZE PLATED WITH 1.27 μm [0.000050] MIN. THICK GOLD IN LOCALIZED AREA, AND 3.0 μm [0.000120] MIN. THICK MATT TIN IN SOLDER AREA OVER 1.27 μm [0.000050] MIN. THICK NICKEL UNDERPLATE
   - **SHIELD:** COPPER Zinc ALLOY PLATED WITH 3.0 μm [0.000120] MIN. THICK REFLOWED TIN.

   △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REG. BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

2. **BULK PACKAGED IN A TRAY**

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**RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT**

**RECOMMENDED PANEL CUTOUT**

COMPONENT SIDE SHOWN